In the Specification

Please replace the paragraph spanning pages 69 and 70 with the following:

After peel of the protective layer (E), the photosensitive resin printing plate precursor 6 was attached on an external drum type plate setter "CDI SPARK" (manufactured by Esko-Graphics NV), equipped with a fiber laser emitting light in the infrared region such that the substrate came into contact with the drum. A test pattern of a resolution of 156 lines per inch (including solid pattern regions, 1% to 99% half tone, 1 to 8 point fine lines, and a 1 to 8 point reverse pattern regions) was drawn, so that the heat-sensitive mask layer (C4) was formed into an image mask (C4'). The heat-sensitive mask layer (C4) in the solid pattern was substantially ablated with laser light under the conditions of a laser power of 9 W and a drum rotational speed of 500 rpm, without negative effects of excessive laser power, such as laser excavation of the surface of the underlying photosensitive resin layer (A2) and deformation of the drawn pattern. In addition, the heat-sensitive mask layer ~~(C3)~~(C4) was resistant to external flaws because of its crosslinked structure. This made it easy to handle the printing plate precursor in attaching on the plate setter. The scratch resistance of the heat-sensitive mask layer (C4) was evaluated in the same manner as in Example 1. As a result, even after 10 reciprocations of rubbing the surface, there was no scratch penetrating through the black heat-sensitive mask layer (C4).